

Title (en)

Heat-receiving member and exhaust pipe heat-releasing system

Title (de)

Wärmeempfangsglied und Abgasrohr-Wärmefreigabesystem

Title (fr)

Élément récepteur de chaleur et système de libération de chaleur de conduit d'échappement

Publication

**EP 2146069 A1 20100120 (EN)**

Application

**EP 09162273 A 20090609**

Priority

JP 2008179380 A 20080709

Abstract (en)

An object of the present invention is to provide a heat-receiving member which demonstrates excellent performance in receiving, by radiation heat transfer, heat energy that is released from a heat source such as an exhaust pipe. A receiving member of the present invention, which receives heat energy released from a heat source, comprises: a base that contains aluminum or an aluminum alloy; and a surface layer that is formed by anodizing a surface of the base.

IPC 8 full level

**F01N 13/08** (2010.01); **F01N 13/10** (2010.01)

CPC (source: EP US)

**C25D 11/022** (2013.01 - EP US); **C25D 11/024** (2013.01 - EP US); **C25D 11/04** (2013.01 - EP US); **C25D 11/22** (2013.01 - EP US);  
**F01N 13/08** (2013.01 - EP US); **F01N 13/102** (2013.01 - EP US); **F28F 13/18** (2013.01 - EP US); **F01N 2530/06** (2013.01 - EP US);  
**F01N 2530/26** (2013.01 - EP US); **F28F 2245/06** (2013.01 - EP US)

Citation (applicant)

- JP H06336923 A 19941206 - TOYOTA MOTOR CORP
- DE 4206247 C1 19930603 - MTU FRIEDRICHSHAFEN GMBH [DE]
- JP S5819654 A 19830204 - NIPPON LIGHT METAL CO

Citation (search report)

- [XY] DE 4206247 C1 19930603 - MTU FRIEDRICHSHAFEN GMBH [DE]
- [X] JP S5819654 A 19830204 - NIPPON LIGHT METAL CO
- [XY] US 5217600 A 19930608 - LE HUONG G [US], et al
- [X] GB 1467039 A 19770316 - OCONNELL J

Cited by

RU2612469C1; DE112009005163B4; EP2500539A1; WO2014118609A1; US8992170B2; US9188251B2; US9534710B2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA RS

DOCDB simple family (publication)

**EP 2146069 A1 20100120; EP 2146069 B1 20131120**; JP 2010018831 A 20100128; US 2010005792 A1 20100114

DOCDB simple family (application)

**EP 09162273 A 20090609**; JP 2008179380 A 20080709; US 49805909 A 20090706